

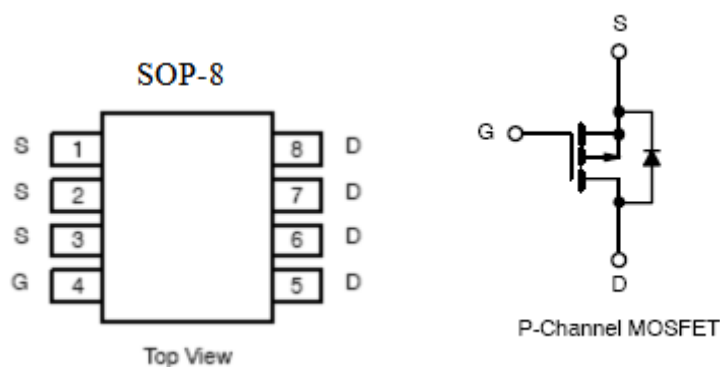
1. Features

- n $R_{DS(on)}=19m\Omega(\text{typ}) @ V_{GS}=10 \text{ V}$
- n Super low gate charge
- n Green device available
- n Excellent Cdv/dt effect decline
- n Advanced high cell density trench technology

2. Description

The KPE4703A is the high cell density trenched P-ch MOSFET's, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications. The KPE4703A meet the RoHs and Green Product requirement.

3. Symbol



4. Absolute maximum ratings

($T_A=25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-source voltage	V_{DSS}	-30	V
Gate-source voltage	V_{GS}	± 20	V
Continuous drain current V_{GS} @-10V ¹	I_D	$T_A=25^{\circ}\text{C}$	-8.0
		$T_A=70^{\circ}\text{C}$	-6.4
Pulsed drain current ²	I_{DM}	-50	A
Single pulse avalanche energy ³	EAS	96.8	mJ
Avalanche current	I_{AS}	-38	A
Total power dissipation ⁴	P_D	$T_A=25^{\circ}\text{C}$	3.1
		$T_A=70^{\circ}\text{C}$	2
Storage Temperature Range	T_{STG}	-55 to 150	$^{\circ}\text{C}$
Operating Junction Temperature Range	T_J	-55 to 150	$^{\circ}\text{C}$

5. Thermal characteristics

Parameter	Symbol	Typ	Max	Units
Thermal resistance, junction-ambient ¹	$R_{\theta JA}$	-	75	$^{\circ}\text{C}/\text{W}$
Thermal resistance, junction-ambient ($t \leq 10\text{s}$)		-	40	
Thermal resistance, Junction-case ¹	$R_{\theta JC}$	-	24	

6. Electrical characteristics

Parameter	Symbol	Test Conditions	(T _J =25°C, unless otherwise noted)			Units
			Min	Typ	Max	
Drain-Source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =-250μA	-30	-	-	V
BV _{DSS} Temperature coefficient	ΔBV _{DSS} / ΔT _J	Reference to 25 °C, I _D =-1mA	-	-0.021	-	V/ °C
Static drain-source on- resistance ²	R _{DS(on)}	V _{GS} =-10V, I _D =-6A	-	19	24	mΩ
		V _{GS} =-4.5V, I _D =-4A	-	27	32	
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA				

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GS(th)G

6. Test circuits and waveforms

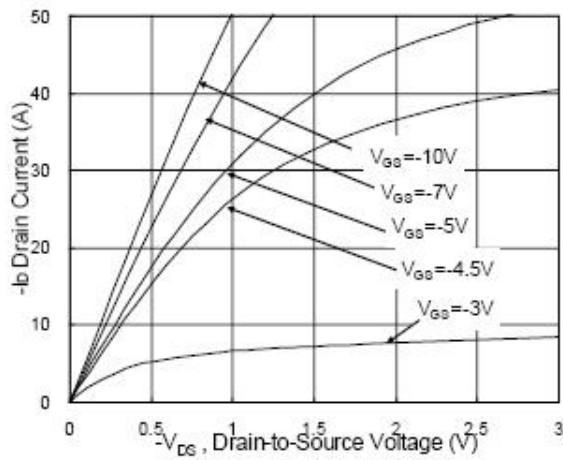


Fig.1 Typical Output Characteristics

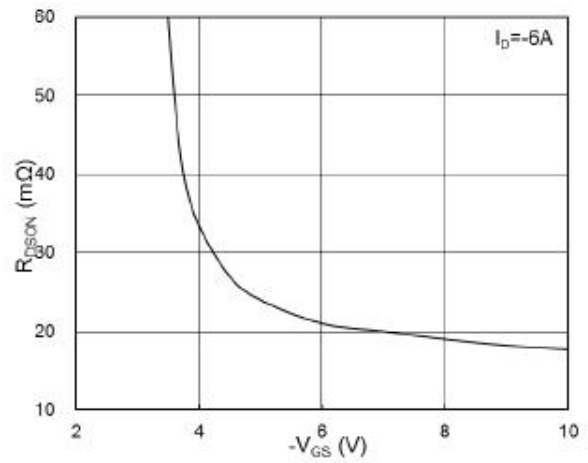


Fig.2 On-Resistance v.s Gate-Source

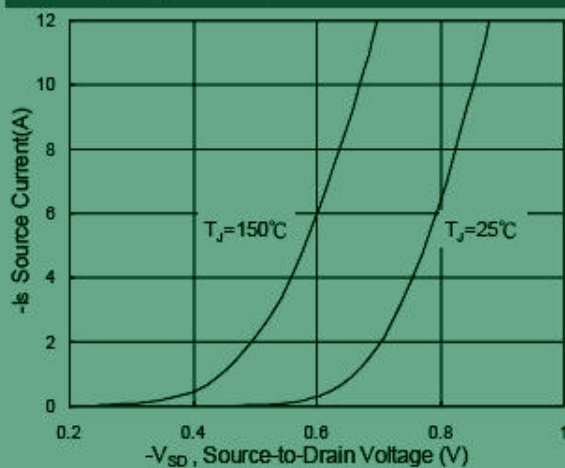


Fig.3 Forward Characteristics of Reverse

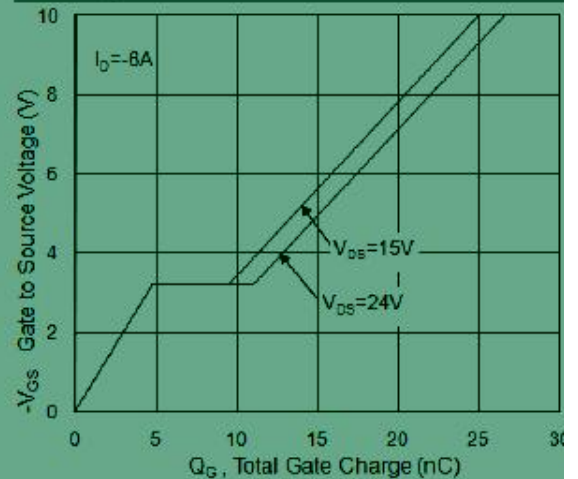


Fig.4 Gate-Charge Characteristics

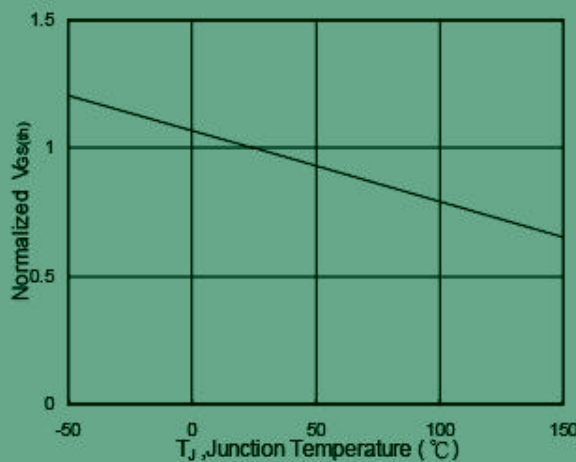


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

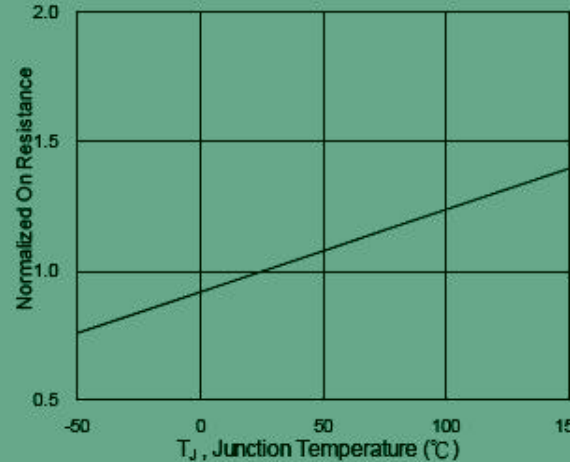


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

